

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BGA 5M1BN6 E6327	**Issued**	08. April 2022
MA#	MA005583454		
Package	PG-TSNP-6-10	**Weight***	0.83 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.093	11.17	11.17	111745	111745
bumps	non noble metal	copper	7440-50-8	0.007	0.82	0.82	8192	8192
leadframe	non noble metal	zinc	7440-66-6	0.001	0.08		758	
	non noble metal	tin	7440-31-5	0.001	0.09		947	
	non noble metal	chromium	7440-47-3	0.001	0.11		1137	
	non noble metal	copper	7440-50-8	0.313	37.61	37.89	376107	378949
encapsulation	organic material	carbon black	1333-86-4	0.001	0.10		954	
	plastics	epoxy resin	-	0.047	5.63		56320	
	inorganic material	silicondioxide	60676-86-0	0.350	42.01	47.74	420012	477286
leadfinish	non noble metal	tin	7440-31-5	0.017	2.07	2.07	20747	20747
solder	noble metal	silver	7440-22-4	0.000	0.01		70	
	non noble metal	tin	7440-31-5	0.002	0.29	0.30	2938	3008
ubm	non noble metal	titanium	7440-32-6	0.000			8	
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	65	73
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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